

MODEL: HSB32-232318 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- aluminum alloy
- black anodized finish



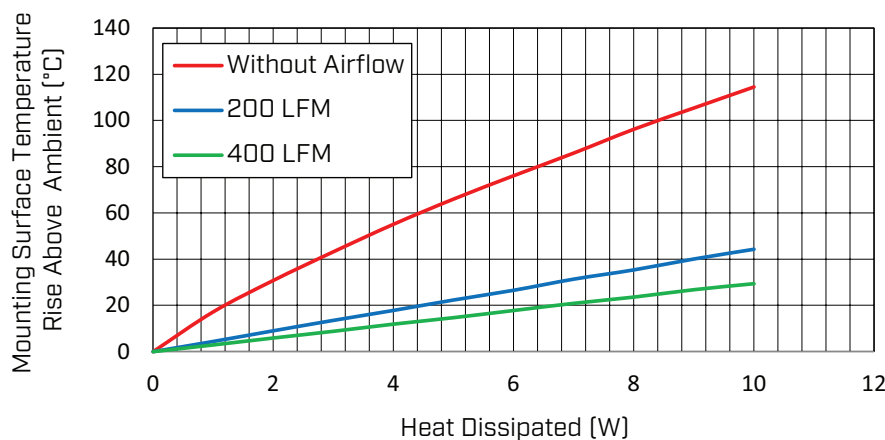
MODEL

	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB32-232318	12.67	17.2	4.4	2.9	5.92

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	17.2	4.4	2.9
2	30.8	9.0	5.9
3	43.2	13.5	8.8
4	55.1	17.8	11.9
5	66.0	22.3	14.7
6	76.1	26.5	17.8
7	85.9	31.3	20.9
8	96.2	35.3	23.6
9	105.4	40.0	26.8
10	114.5	44.2	29.4

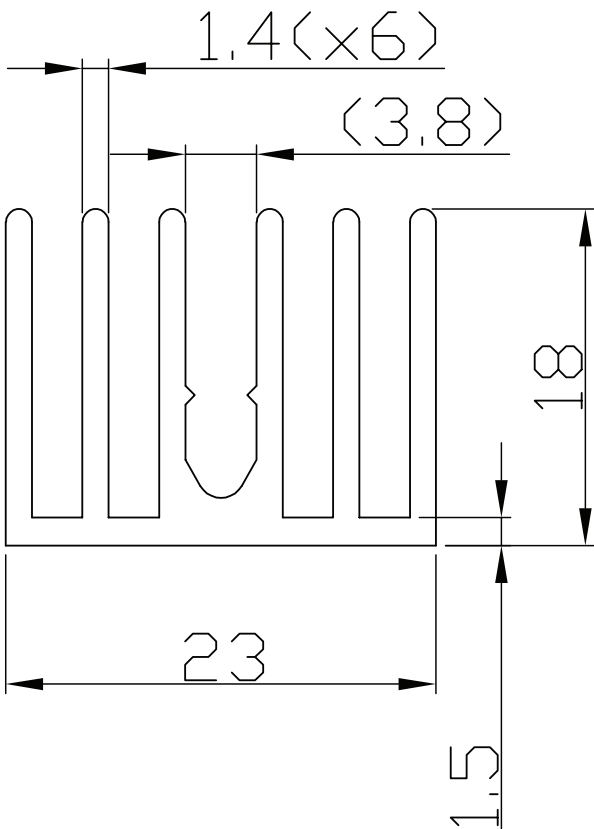
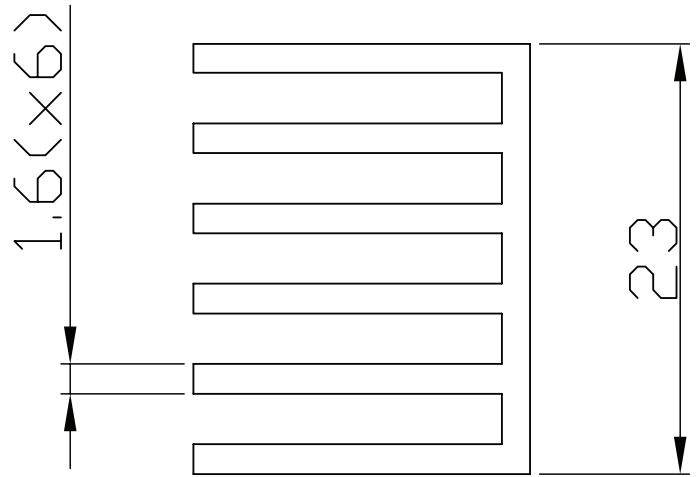
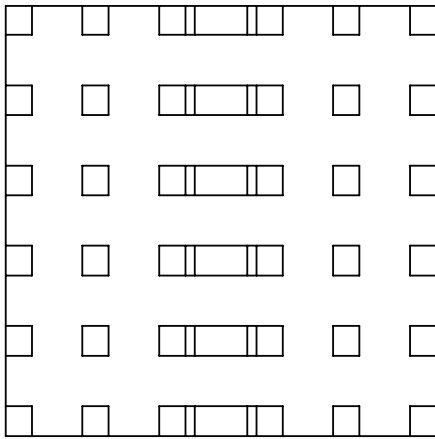


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	14 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



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